

Technical Data Sheet

● Purpose of use and softening temperature of applicable frit for electronic materials

Purpose of use	Applicable material	Softning temp. [°C]								Typical applications	
		300	400	500	600	700	800	900	1000		
hermetic sealing at lot temp.	Glass Ceramics Metal(Iron)				Bi ₂ O ₃ -B ₂ O ₃ 系					Package for IC, etc.	
Insulation	Ceramics Metal		P ₂ O ₅ -R ₂ O系		Bi ₂ O ₃ -B ₂ O ₃ 系		R ₂ O-ZnO-B ₂ O ₃ 系		R ₂ O-B ₂ O ₃ -SiO ₂ 系		Magnetic material, Resistor, Varistor, etc. Cover coating on electrode
Bonding, Binding	Ceramics Metal powder		Bi ₂ O ₃ -B ₂ O ₃ 系				RO-B ₂ O ₃ -SiO ₂ 系			Binder for Ceramics, Binder for Printed electrode	
Smoothing	Ceramics						RO-B ₂ O ₃ -SiO ₂ 系			Grazed substrate	
Low temperature sintering	Ceramics						RO-B ₂ O ₃ -SiO ₂ 系			LTCC substrate	

※ Even for applications other than the above, we will make proposals according to your needs.
For more information and samples, please contact us using the contact form below.



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